

# BCR16CM-12LB

## Triac

### Medium Power Use

(The product guaranteed maximum junction temperature of 150°C)

REJ03G0457-0300

Rev.3.00

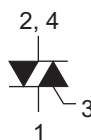
Nov 30, 2007

## Features

- $I_{T(RMS)}$  : 16 A
- $V_{DRM}$  : 600 V
- $I_{FGTI}$ ,  $I_{RGTI}$ ,  $I_{RGT III}$  : 30 mA (20 mA)<sup>Note6</sup>
- Non-Insulated Type
- Planar Passivation Type

## Outline

RENESAS Package code: PRSS0004AA-A  
(Package name: TO-220)



1. T<sub>1</sub> Terminal
2. T<sub>2</sub> Terminal
3. Gate Terminal
4. T<sub>2</sub> Terminal

## Applications

Contactless AC switch, light dimmer, electronic flasher unit, control of household equipment such as TV sets, stereo systems, refrigerator, washing machine, infrared kotatsu, carpet, electric fan, solenoid driver, small motor control, copying machine, electric tool, electric heater control, and other general purpose control applications

## Warning

1. Refer to the recommended circuit values around the triac before using.
2. Be sure to exchange the specification before using. Otherwise, general triacs with the maximum junction temperature of 125°C will be supplied.

## Maximum Ratings

| Parameter  | Symbol    | Voltage class | Unit |
|--|-----------|---------------|------|
|  |           | 12            |      |
| Repetitive peak off-state voltage <sup>Note1</sup>     | $V_{DRM}$ | 600           | V    |
| Non-repetitive peak off-state voltage <sup>Note1</sup> | $V_{DSM}$ | 720           | V    |

**BCR16CM-12LB (The product guaranteed maximum junction temperature of 150°C)**

| Parameter                      | Symbol      | Ratings      | Unit                 | Conditions   |
|--------------------------------|-------------|--------------|----------------------|--|
| RMS on-state current           | $I_T$ (RMS) | 16           | A                    | Commercial frequency, sine full wave 360° conduction, $T_c = 125^\circ\text{C}$ <sup>Note3</sup> |
| Surge on-state current         | $I_{TSM}$   | 170          | A                    | 60Hz sinewave 1 full cycle, peak value, non-repetitive   |
| $I^2t$ for fusing              | $I^2t$      | 121          | $\text{A}^2\text{s}$ | Value corresponding to 1 cycle of half wave 60Hz, surge on-state current                         |
| Peak gate power dissipation    | $P_{GM}$    | 5.0          | W                    |  |
| Average gate power dissipation | $P_{G(AV)}$ | 0.5          | W                    |  |
| Peak gate voltage              | $V_{GM}$    | 10           | V                    |  |
| Peak gate current              | $I_{GM}$    | 2            | A                    |  |
| Junction temperature           | $T_j$       | - 40 to +150 | $^\circ\text{C}$     |  |
| Storage temperature            | $T_{stg}$   | - 40 to +150 | $^\circ\text{C}$     |  |
| Mass                           | —           | 2.0          | g                    | Typical value  |

Notes: 1. Gate open.

**Electrical Characteristics**

| Parameter   | Symbol           | Min.    | Typ. | Max.                | Unit                      | Test conditions   |
|---|------------------|---------|------|---------------------|---------------------------|---|
| Repetitive peak off-state current                                       | $I_{DRM}$        | —       | —    | 2.0                 | mA                        | $T_j = 150^\circ\text{C}$ , $V_{DRM}$ applied   |
| On-state voltage  | $V_{TM}$         | —       | —    | 1.5                 | V                         | $T_c = 25^\circ\text{C}$ , $I_{TM} = 25\text{ A}$ , Instantaneous measurement           |
| Gate trigger voltage <sup>Note2</sup>                                   | I $V_{FGTI}$     | —       | —    | 1.5                 | V                         | $T_j = 25^\circ\text{C}$ , $V_D = 6\text{ V}$ , $R_L = 6\ \Omega$ , $R_G = 330\ \Omega$ |
|   | II $V_{RGTI}$    | —       | —    | 1.5                 | V                         |   |
|   | III $V_{RGTIII}$ | —       | —    | 1.5                 | V                         |   |
| Gate trigger current <sup>Note2</sup>                                   | I $I_{FGTI}$     | —       | —    | 30 <sup>Note6</sup> | mA                        | $T_j = 25^\circ\text{C}$ , $V_D = 6\text{ V}$ , $R_L = 6\ \Omega$ , $R_G = 330\ \Omega$ |
|   | II $I_{RGTI}$    | —       | —    | 30 <sup>Note6</sup> | mA                        |   |
|   | III $I_{RGTIII}$ | —       | —    | 30 <sup>Note6</sup> | mA                        |   |
| Gate non-trigger voltage  | $V_{GD}$         | 0.2/0.1 | —    | —                   | V                         | $T_j = 125^\circ\text{C}/150^\circ\text{C}$ , $V_D = 1/2 V_{DRM}$                       |
| Thermal resistance  | $R_{th(j-c)}$    | —       | —    | 1.4                 | $^\circ\text{C}/\text{W}$ | Junction to case <sup>Note3 Note4</sup>   |
| Critical-rate of rise of off-state commutating voltage <sup>Note5</sup> | $(dv/dt)_c$      | 10/1    | —    | —                   | $\text{V}/\mu\text{s}$    | $T_j = 125^\circ\text{C}/150^\circ\text{C}$   |

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

3. Case temperature is measured at the  $T_2$  tab 1.5 mm away from the molded case.

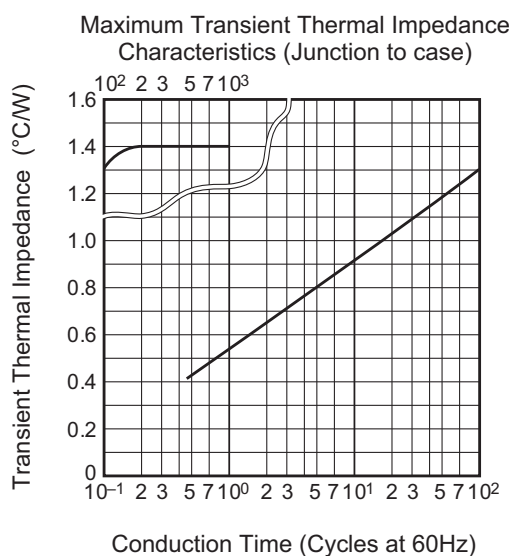
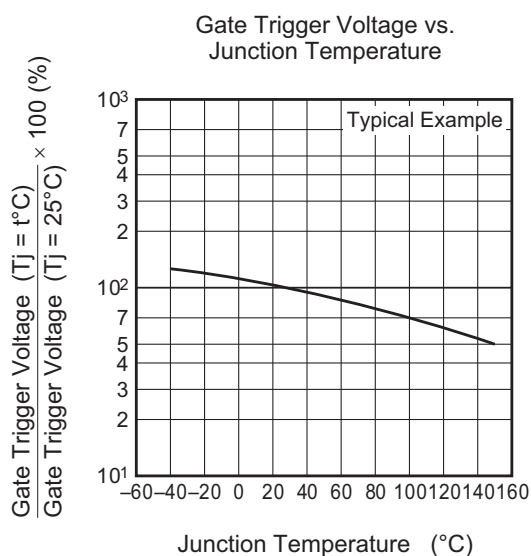
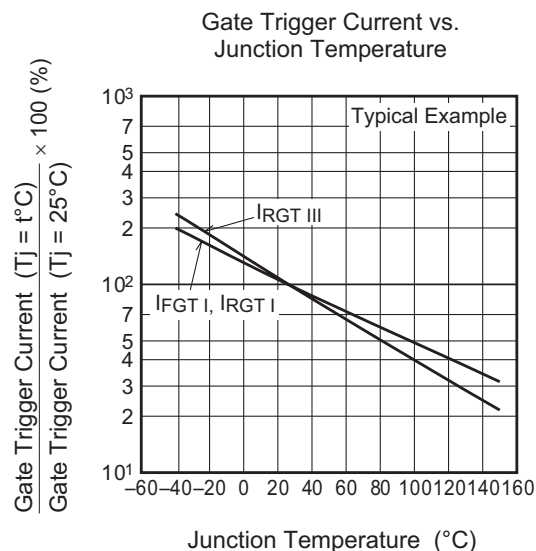
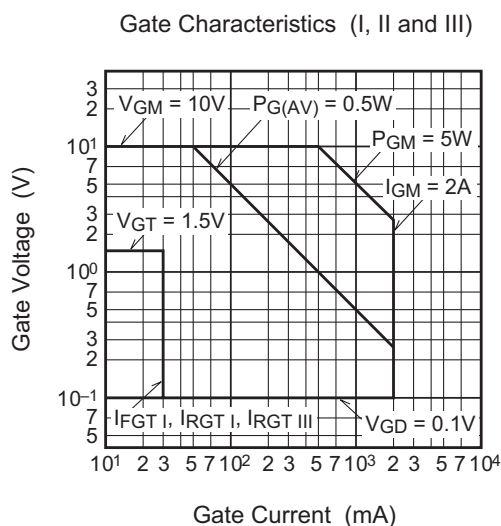
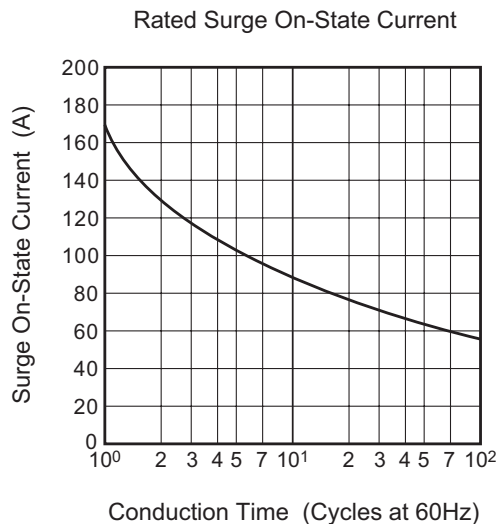
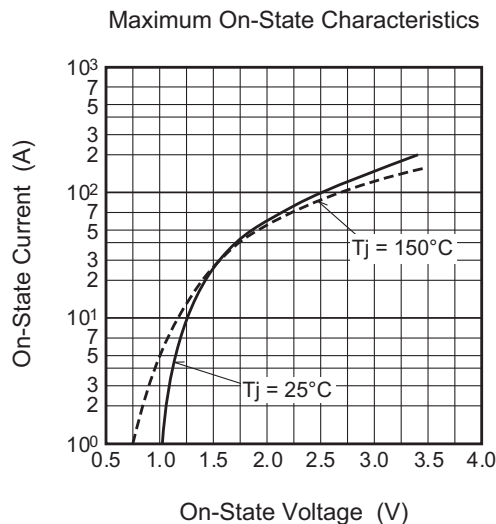
4. The contact thermal resistance  $R_{th(c-f)}$  in case of greasing is  $1.0^\circ\text{C}/\text{W}$ .

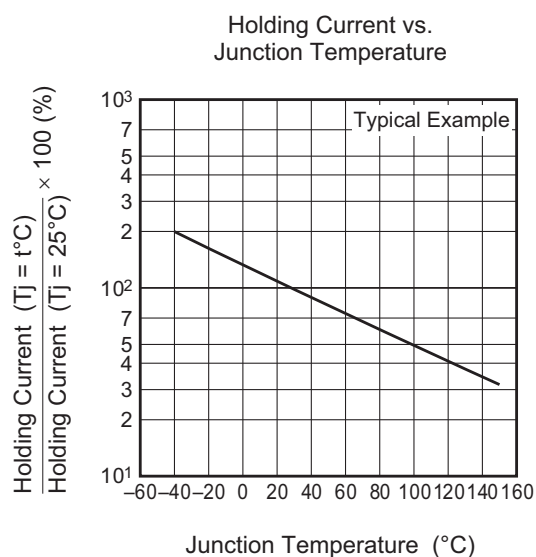
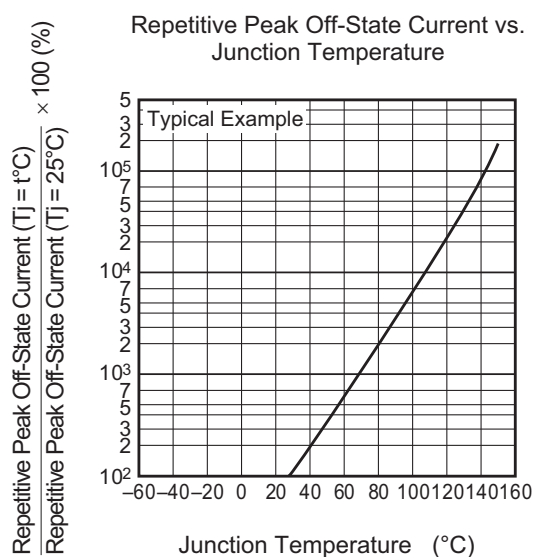
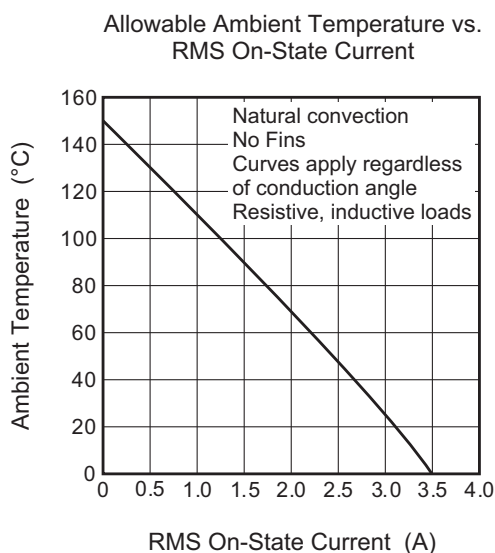
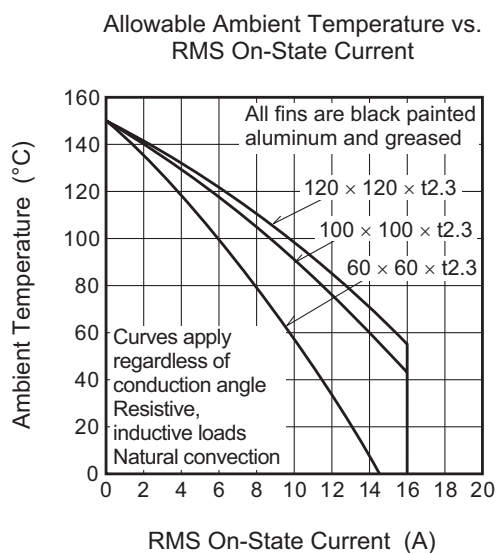
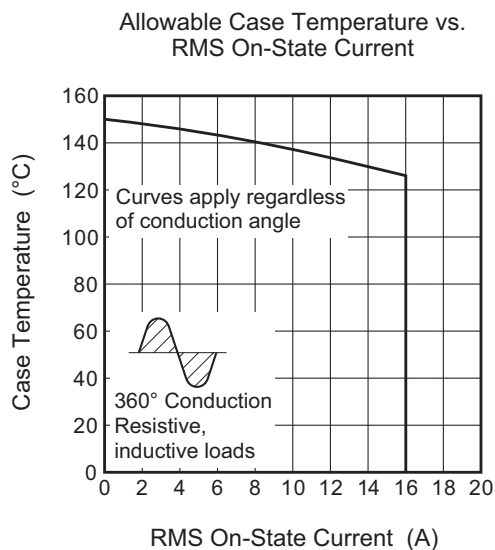
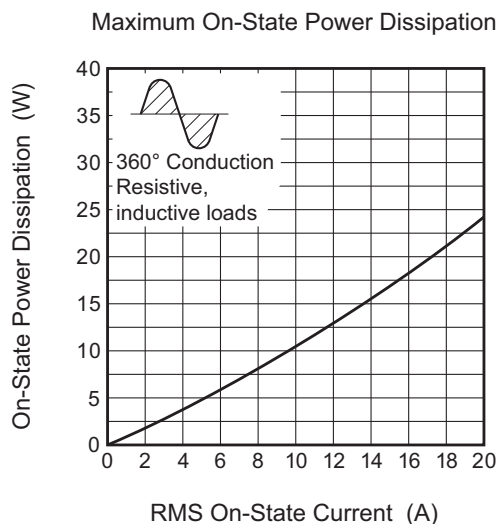
5. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

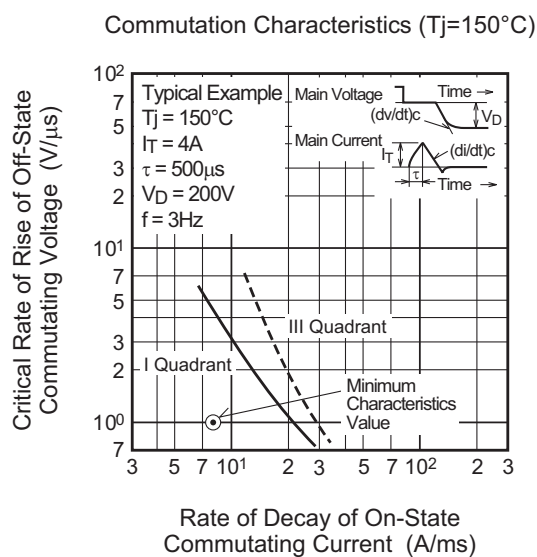
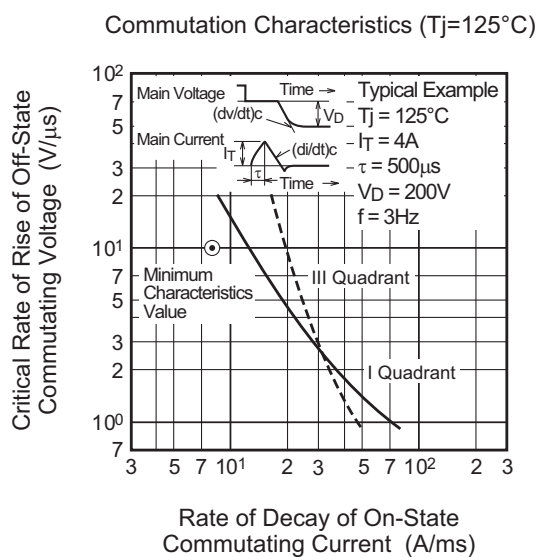
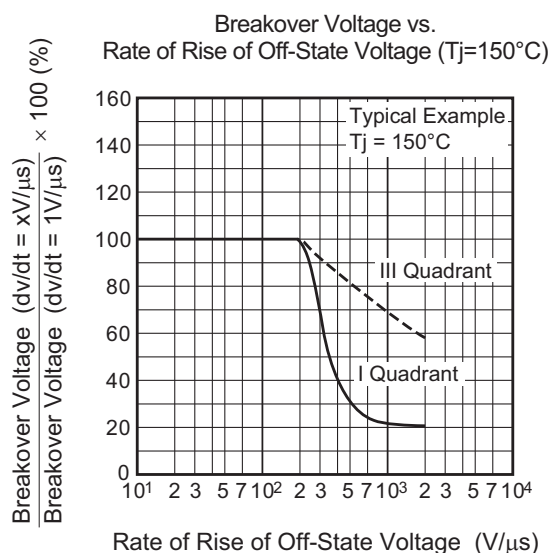
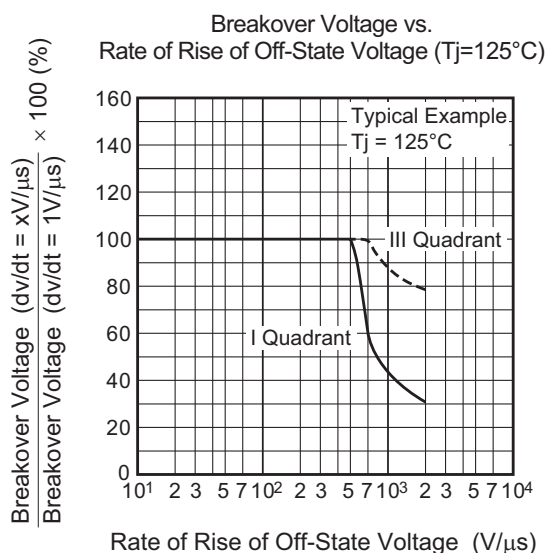
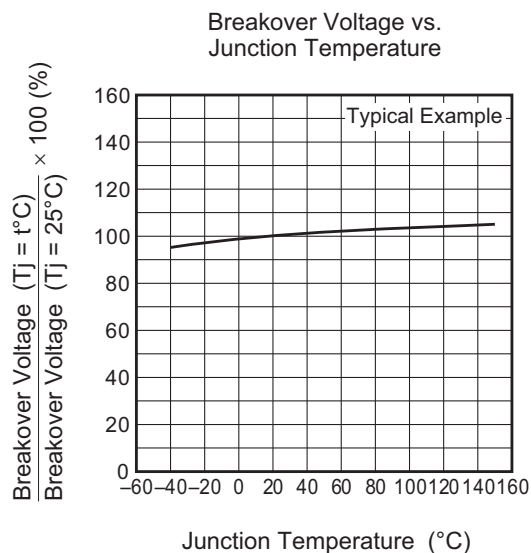
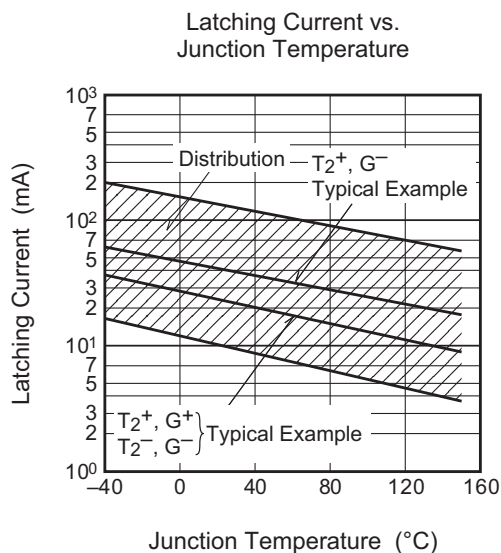
6. High sensitivity ( $I_{GT} \leq 20\text{ mA}$ ) is also available. ( $I_{GT}$  item: 1)

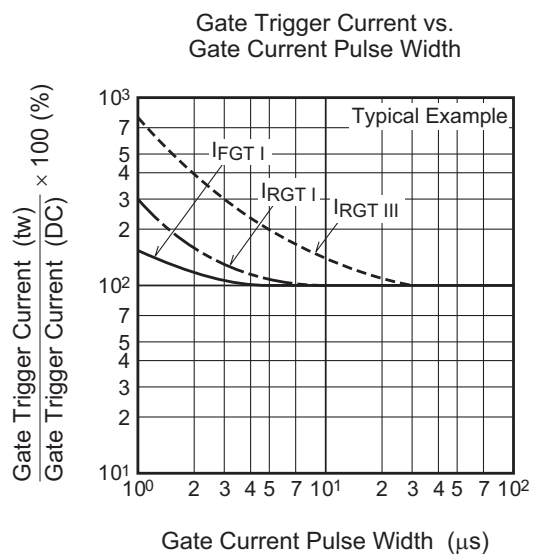
| Test conditions   | Commutating voltage and current waveforms (inductive load) |
|---|--|
| 1. Junction temperature<br>$T_j = 125^\circ\text{C}/150^\circ\text{C}$<br>2. Rate of decay of on-state commutating current<br>$(di/dt)_c = -8.0\text{ A/ms}$<br>3. Peak off-state voltage<br>$V_D = 400\text{ V}$ |  |

## Performance Curves

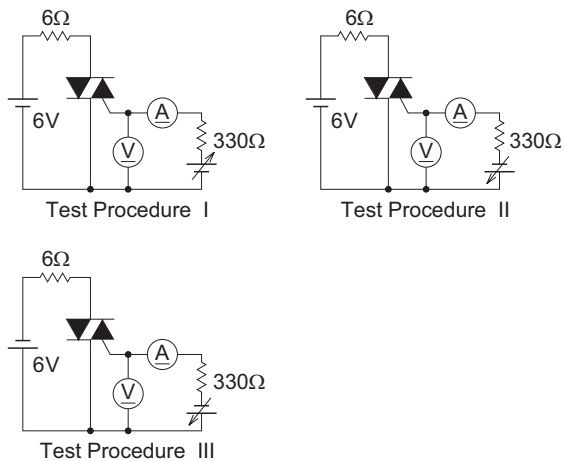




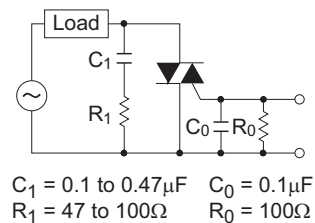




Gate Trigger Characteristics Test Circuits



Recommended Circuit Values Around The Triac



## Package Dimensions

| Package Name | JEITA Package Code | RENESAS Code | Previous Code | MASS[Typ.] | Unit: mm |
|--------------|--------------------|--------------|---------------|------------|----------|
| TO-220       | SC-46              | PRSS0004AA-A | —             | 2.0g       |          |

The drawing illustrates the mechanical specifications of the BCR16CM-12LB TO-220 package. The top view shows a rectangular body with a width of 10.5Max mm and a height of 16Max mm. A central circular feature has a diameter of  $\phi 3.6$  mm. The side view shows a total height of 12.5Min mm, with a lead height of 3.8Max mm and a lead thickness of 0.8 mm. The lead spacing is 2.54 mm. The bottom view shows a width of 4.5Max mm. The lead form is shown in a separate view with a width of 0.5 mm and a height of 2.6 mm.

## Order Code

| Lead form     | Standard packing        | Quantity | Standard order code           | Standard order code example |
|---------------|-------------------------|----------|-------------------------------|-----------------------------|
| Straight type | Vinyl sack              | 100      | Type name                     | BCR16CM-12LB                |
| Lead form     | Plastic Magazine (Tube) | 50       | Type name – Lead forming code | BCR16CM-12LB-A8             |

Note : Please confirm the specification about the shipping in detail.

Notes:

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